

Series HXP-600

600 W Power Resistor at 85°C bottom case



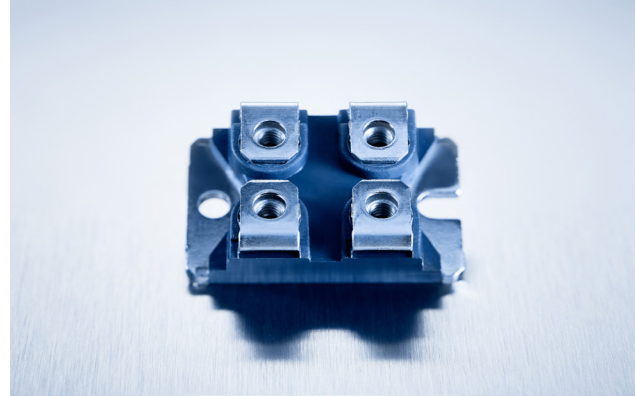
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Due to our Non-Inductive design, the HXP series is ideally suited for high-frequency and pulse-loading applications. Through direct mounting on a heat sink, significant cost advantage can be realized. Main applications are: variable speed drives, power supplies, control devices, telecommunications, robotics, motor controls and other switching devices.

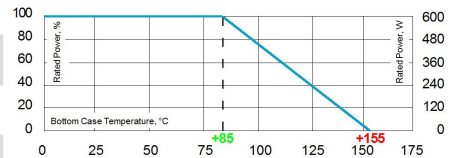
Features

- multiple resistors in 1 package
- Non-Inductive design
- ROHS compliant
- Materials in accordance with UL 94 V-0
- General pulse load information (ask for details)



Technical Specifications

| | |
|---|---|
| Resistance value | 0.15 Ω ≤ 5 KΩ (higher values on special request) |
| Resistance tolerance | ±5 % to 10 % (configuration 4,5,6 only tolerance ±10% possible) |
| Temperature coefficient | > 1R: ±150 ppm/°C (at +85°C ref. to +25°C) lower TCR on special request for limited ohmic values |
| Power rating | up to 600 W at 85°C bottom case temperature (see configurations) |
| Short time overload | 1.25x rated power at 85°C bottom case temperature for 10 sec., ΔR = 0.4% max. (for conf. 1, 2 and 3) |
| Maximum working voltage | 1,000 V DC (up to 2,000 V on special request = "S"-version) |
| Partial discharge | up to 2,000 V on 80pC (Tests only on special request) |
| Voltage proof | dielectric strength up to 4,000 V DC against ground |
| Insulation resistance | > 10 GΩ at 1,000 V DC |
| Isolation voltage between R1 & R2 & R3 | 500 V DC (1,000 V DC on special request) |
| Protection class | acc. to IEC 950/CSA22.2 950/M-89 and EN 60950.88:2 |
| Comparative Tracking Index (CTI) | standard 500 V |
| Heat resistance to cooling plate | Rth < 0.12 K/W |
| Capacitance/mass | 45 pF (typical), measuring frequency 10 kHz |
| Serial inductivity | HXP-1 typical 40 nH, measuring frequency 10 kHz |
| Working temperature range | -55°C to +155°C |
| Mounting - torque for base plate (static) | 1.3 Nm to 1.5 Nm M4 screws |
| Mounting - torque for contacts (static) | 1.1 Nm to 1.3 Nm M4 screws, screw-in depth max. 5mm |
| Weight | ~27 g |



Derating (thermal resist.) HXP-600:
8.33 W/K (0.12 K/W) (for conf. 1, 2 and 3)

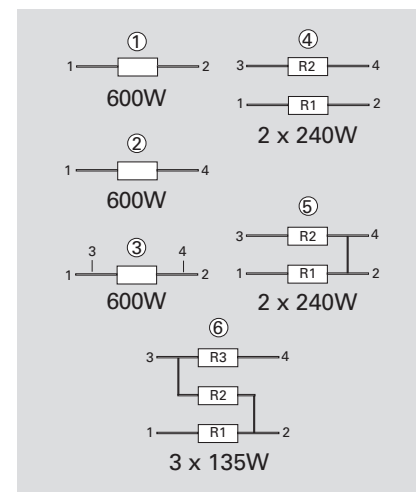
Best results can be reached by using a thermal transfer compound with a heat conductivity of at least 2.9 W/mK. The flatness of the cooling plate must be better than 0.05 mm overall. Surface roughness should not exceed 6.4 μm.

How to make an order

HXP-600-Configuration_Ohmic Value_Tolerance

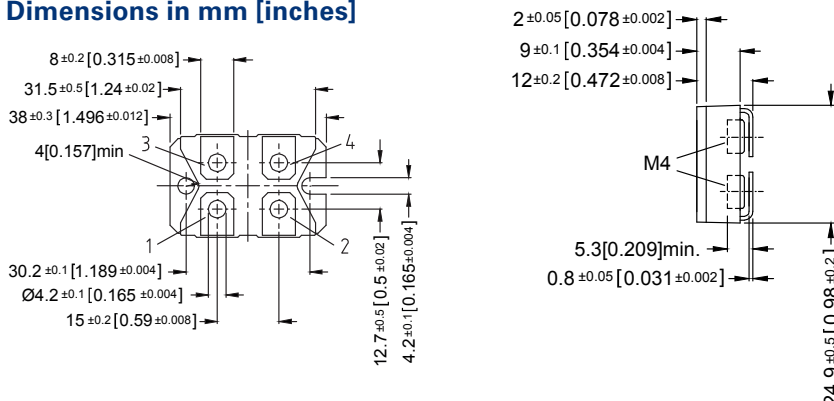
For example:
HXP-600-1 27R 10% or
HXP-600-4 2x220R 5%

Configurations (P / package)



Version 5: ohmic value between contact 2 and 4 = 3mΩ

Dimensions in mm [inches]



The above spec. sheet features our standard products. For further options please contact our local EBG representative or contact us directly.

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